MA3X100 (MA10100)

Silicon epitaxial planar type

For switching circuits

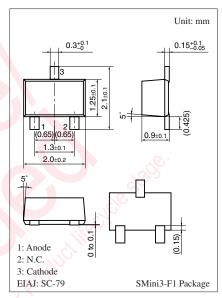
■ Features

- High breakdown voltage: $V_R = 200 \text{ V}$
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25$ °C

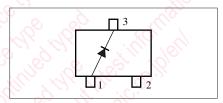
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	200	V
Repetitive peak reverse voltage	V _{RRM}	250	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Repetitive peak forward current	I _{FRM}	225	mA
Non-repetitive peak forward surge current *	I_{FSM}	500	mA
Junction temperature	T_{j}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

Note) *: t = 1 s



Marking Symbol: M3A

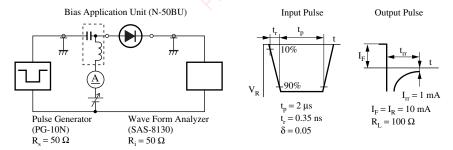
Internal Connection



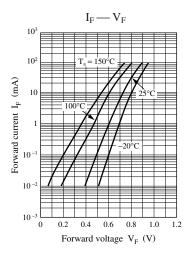
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

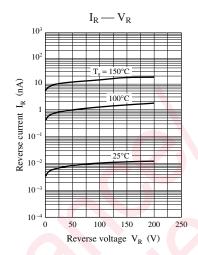
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 100 \text{ mA}$	6		1.2	V
Reverse current	I_R	V _R = 200 V			1.0	μΑ
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$			3.0	pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$ $I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$			60	ns

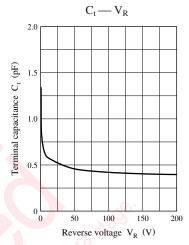
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. Absolute frequency of input and output is 20 MHz.
 - 3. *: t_{rr} measurement circuit



Note) The part number in the parenthesis shows conventional part number.







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